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Part 5-5: Optoelectronic devices – Photocouplers**

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CONTENTS

FOREWORD.....	5
1 Scope.....	7
2 Normative references	7
3 Terms and definitions	8
3.7 Symbols for limiting values (absolute maximum system) over the operating temperature range, unless otherwise stated.....	16
4 Electrical characteristics.....	16
4.1 Phototransistor output photocoupler.....	16
4.2 Phototriac output photocoupler or solid state opto-relay.....	17
5 Photocouplers providing protection against electric shock	18
5.1 General.....	18
5.2 Type	18
5.3 Ratings	18
5.3.1 Datasheet ratings	18
5.3.2 Safety ratings	18
5.3.3 Functional ratings.....	18
5.3.4 Rated isolation voltages	18
5.4 Electrical safety requirements	18
5.5 Electrical, environmental and/or endurance test information (supplementary information)	19
5.5.1 Test and test sequence	19
5.5.2 Routine test.....	19
5.5.3 Sample test	20
5.5.4 Type test	20
6 Measuring methods for photocouplers	27
6.1 Current transfer ratio $H_{f(ctr)}$	27
6.2 Input-to-output capacitance C_{IO}	28
6.3 Isolation resistance between input and output R_{IO}	29
6.4 Isolation test	30
6.5 Partial discharges of photocouplers	31
6.6 Collector-emitter saturation voltage $V_{CE(sat)}$ of a photocoupler.....	34
6.6.1 Collector-emitter saturation voltage (DC method).....	34
6.6.2 Collector-emitter saturation voltage (pulse method)	34
6.7 Switching times t_{on} , t_{off} of a photocoupler.....	35
6.8 Peak off-state current I_{DRM}	37
6.9 Peak on-state voltage V_{TM}	39
6.10 DC off-state current I_{BD}	41
6.11 DC on-state voltage V_T	42
6.12 Holding current I_H	42
6.13 Critical rate of rise of off-state voltage dV/dt	43
6.14 Trigger input current I_{FT}	46
6.15 Measuring methods of common mode transient immunity (CMTI) for photocouplers	47
7 Testing methods of electrical ratings for phototriac couplers.....	49
7.1 Repetitive peak off-state voltage V_{DRM}	49

7.2	DC off-state voltage V_{BD}	50
Annex A (normative)	Input/output safety test.....	51
A.1	Purpose	51
A.2	Circuit diagram	51
A.3	Circuit description	51
A.4	Precautions to be observed.....	51
A.5	Measurement procedure	51
A.6	Specified conditions.....	51
Bibliography	52
Figure 1	– Time intervals for method a).....	12
Figure 2	– Time intervals for method b).....	13
Figure 3	– Test voltage	15
Figure 4	– Measurement circuit.....	27
Figure 5	– Measurement circuit for input to output capacitance	29
Figure 6	– Measurement circuit for isolation resistance.....	29
Figure 7	– Test circuit for withstanding isolation voltage	30
Figure 8	– Partial discharge test circuit	31
Figure 9	– Complete test arrangement connections for calibration	32
Figure 10	– DC measurement circuit	34
Figure 11	– Pulse measurement circuit	35
Figure 12	– Switching time measurement circuit	36
Figure 13	– Switching times	37
Figure 14	– Measurement circuit for peak off-state current.....	38
Figure 15	– Waveforms of the peak off-state voltage and current.....	39
Figure 16	– Measurement circuit for peak on-state voltage	40
Figure 17	– Waveforms of the peak on-state voltage and current	41
Figure 18	– Measurement circuit for DC off-state current	41
Figure 19	– Measurement circuit for DC on-state voltage	42
Figure 20	– Measurement circuit for holding current.....	43
Figure 21	– Measurement circuit for critical rate of rise of off-state voltage	44
Figure 22	– Exponential waveform of the off-voltage (V_D)	45
Figure 23	– Linear pulse form of the off-voltage (V_D).....	45
Figure 24	– Measurement circuit for the trigger input current	46
Figure 25	– Output terminal voltage versus input forward current.....	46
Figure 26	– Common mode transient immunity (CMTI) measurement circuit for photocoupler.....	47
Figure 27	– Typical waveforms of the common mode pulse (V_{CM}) and photocoupler output (V_O).....	49
Figure A.1	– Circuit diagram	51
Table 1	– Phototransistor electrical characteristics	16
Table 2	– Phototriac electrical characteristics	17
Table 3	– Datasheet characteristics	19

Table 4 – Tests and test sequence for photocoupler providing protection against electrical shock	26
Table 5 – Test conditions	27
Table 6 – Specified conditions for methods a) and b).....	33

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –**Part 5-5: Optoelectronic devices –
Photocouplers**

FOREWORD

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International Standard IEC 60747-5-5 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2007 and Amendment 1:2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) optional data sheet basic insulation rating in accordance with IEC 60664-1:2007, 6.1.3.5;
- b) editorial corrections on the use of V_{IORM} ;
- c) editorial corrections on Figure 2: Time intervals for method b);
- d) addition of an alternative surge pulse V_{IOSM} test method.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47E/706/FDIS	47E/714/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60747 series, published under the general title *Semiconductor devices*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

SEMICONDUCTOR DEVICES –

Part 5-5: Optoelectronic devices – Photocouplers

1 Scope

This part of IEC 60747 specifies the terminology, essential ratings, characteristics, safety tests, as well as the measuring methods for photocouplers.

NOTE The term "optocoupler" can also be used instead of "photocoupler".

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1:2013, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-1, *Environmental testing – Part 2-1: Tests – Test A: Cold*

IEC 60068-2-2, *Environmental testing – Part 2-2: Tests – Test B: Dry heat*

IEC 60068-2-6, *Environmental testing – Part 2-6: Tests – Test Fc: Vibration (sinusoidal)*

IEC 60068-2-14, *Environmental testing – Part 2-14: Tests – Test N: Change of temperature*

IEC 60068-2-17, *Basic environmental testing procedures – Part 2-17: Tests – Test Q: Sealing*

IEC 60068-2-20, *Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads*

IEC 60068-2-27, *Environmental testing – Part 2-27: Tests – Test Ea and guidance: Shock*

IEC 60068-2-30, *Environmental testing – Part 2-30: Tests – Test Db: Damp heat, cyclic (12 h + 12 h cycle)*

IEC 60068-2-58, *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)*

IEC 60068-2-78, *Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state*

IEC 60112, *Method for the determination of the proof and the comparative tracking indices of solid insulating materials*

IEC 60216-1, *Electrical insulating materials – Thermal endurance properties – Part 1: Ageing procedures and evaluation of test results*

IEC 60216-2, *Electrical insulating materials – Thermal endurance properties – Part 2: Determination of thermal endurance properties of electrical insulating materials – Choice of test criteria*

IEC 60664-1:2007, *Insulation coordination for equipment within low-voltage systems – Part 1: Principles, requirements and tests*

IEC 60672-2, *Ceramic and glass insulating materials – Part 2: Methods of test*

IEC 60695-11-5, *Fire hazard testing – Part 11-5: Test flames – Needle-flame test method – Apparatus, confirmatory test arrangement and guidance*

IEC 61000-4-5, *Electromagnetic compatibility (EMC) – Part 4-5: Testing and measurement techniques – Surge immunity test*

IEC 62368-1:2018, *Audio/video, information and communication technology equipment – Part 1: Safety requirements*